

# 3. Serial Configuration Devices (EPCS1, EPCS4, EPCS16, EPCS64, and EPCS128) Data Sheet

#### C51014-3.3

# **Features**

The serial configuration devices provide the following features:

- 1-, 4-, 16-, 64-, and 128-Mbit flash memory devices that serially configure Arria<sup>®</sup> series, Cyclone<sup>®</sup> series, all device families in the Stratix<sup>®</sup> series except the Stratix device family, and FPGAs using the active serial (AS) configuration scheme
- Easy-to-use four-pin interface
- Low cost, low-pin count, and non-volatile memory
- Low current during configuration and near-zero standby mode current
- 2.7-V to 3.6-V operation
- EPCS1 and EPCS4 available in 8-pin small outline integrated circuit (SOIC) package. EPCS16 available in 8-pin or 16-pin SOIC packages. EPCS64 and EPCS128 available in 16-pin SOIC package
- Enables the Nios<sup>®</sup> processor to access unused flash memory through AS memory interface
- Re-programmable memory with more than 100,000 erase/program cycles
- Write protection support for memory sectors using status register bits
- In-system programming support with SRunner software driver
- In-system programming support with USB Blaster<sup>™</sup>, EthernetBlaster, or ByteBlaster<sup>™</sup> II download cables
- Additional programming support with the Altera<sup>®</sup> Programming Unit (APU) and programming hardware from BP Microsystems, System General, and other vendors
- Delivered with the memory array erased (all the bits set to 1)
- The term "serial configuration devices" used in this document refers to Altera EPCS1, EPCS4, EPCS16, EPCS64, and EPCS128.

# **Functional Description**

With SRAM-based devices that support active serial configuration, configuration data must be reloaded each time the device powers up, the system reconfigures, or when new configuration data is required. Serial configuration devices are flash memory devices with a serial interface that can store configuration data for FPGA devices that support active serial configuration and reload the data to the device upon power-up or reconfiguration. Table 3–1 summarizes the features of the Altera configuration devices and the amount of configuration space they hold.

Device	Memory Size (bits)	On-Chip Decompression Support	ISP Support	Cascading Support	Reprogrammable	Operating Voltage (V)
EPCS1	1,048,576	No	Yes	No	Yes	3.3
EPCS4	4,194,304	No	Yes	No	Yes	3.3
EPCS16	16,777,216	No	Yes	No	Yes	3.3
EPCS64	67,108,864	No	Yes	No	Yes	3.3
EPCS128	134,217,728	No	Yes	No	Yes	3.3

Table 3–1. Altera Configuration Devices (Note 1), (2)

Notes to Table 3-1:

(1) To program these devices using Altera Programming Unit or Master Programming Unit, refer to Altera Programming Hardware Data Sheet.

(2) The EPCS device can be re-programmed in system with Byte Blaster II download cable or an external microprocessor using SRunner. For more information about SRunner, refer to the AN418, SRunner: An Embedded Solution for EPCS Programming.

For an 8-pin SOIC package, you can migrate vertically from the EPCS1 to the EPCS4 or EPCS16 because the EPCS devices are offered in the same device package. Similarly, for a 16-pin SOIC package, you can migrate vertically from the EPCS16 to the EPCS64 or EPCS128.

Use the compression ratio calculation to determine the FPGA device to fit the EPCS.

Example 3–1. Compression Ratio Calculation

EP4SGX530 = 189,000,000 bits

EPCS128 = 134,217,728 bits

Preliminary data indicates that compression typically reduces the configuration bitstream size by 35% to 55%. We take the worst case that is 35% compression.

189,000,000 bits × 0.65 = 122,850,000 bits It fits EPCS128 device.

With the new data-decompression feature in Arria series, Cyclone series, and all device families in the Stratix series except the Stratix device family, you can use smaller serial configuration devices to configure larger FPGAs.

Serial configuration devices cannot be cascaded.

 For more information about the FPGA decompression feature, refer to the configuration chapter in the appropriate device handbook. The serial configuration devices are designed to configure the Cyclone series and all device families in the Stratix series except the Stratix device family. It cannot configure other existing Altera FPGA device families.

Figure 3–1 shows the serial configuration device block diagram.





## Accessing Memory in Serial Configuration Devices

You can access the unused memory locations of the serial configuration device to store or retrieve data through the Nios processor and SOPC Builder. SOPC Builder is an Altera tool for creating bus-based (especially microprocessor-based) systems in Altera devices. SOPC Builder assembles library components such as processors and memories into custom microprocessor systems.

SOPC Builder includes the EPCS device controller core, which is an interface core specifically designed to work with the serial configuration device. With this core, you can create a system with a Nios embedded processor that allows software access to any memory location within the serial configuration device.



For more information about accessing memory within the serial configuration device, refer to the *Active Serial Memory Interface Data Sheet*.

# **Active Serial FPGA Configuration**

The following Altera FPGAs support Active Serial (AS) configuration scheme with serial configuration devices:

- Arria series
- Cyclone series
- all device families in the Stratix series except the Stratix device family

This section is only relevant for FPGAs that support the AS configuration scheme.

There are four signals on the serial configuration device that interface directly with the FPGA's control signals. The serial configuration device signals DATA, DCLK, ASDI, and *n*CS interface with DATA0, DCLK, ASDO, and *n*CSO control signals on the FPGA, respectively. Figure 3–2 shows a serial configuration device programmed via a download cable, which configures an FPGA in AS mode. Figure 3–3 shows a serial configuration device programmer configuration an FPGA in AS configuration mode.

For more information about the serial configuration device pin description, refer to Table 3–23.

**Figure 3–2.** Altera FPGA Configuration in AS Mode (Serial Configuration Device Programmed Using Download Cable) (*Note 1*), (4)



#### Notes to Figure 3-2:

- (1) For the  $V_{CC}$  value, refer to the respective FPGA family handbook Configuration chapter.
- (2) Serial configuration devices cannot be cascaded.
- (3) Connect the FPGA MSEL [] input pins to select the AS configuration mode. For details, refer to the respective FPGA family chapter in the Configuration Handbook.
- (4) For more information about configuration pin I/O requirements in an AS scheme for an Altera FPGA, refer to the respective FPGA family handbook Configuration chapter.

**Figure 3–3.** Altera FPGA Configuration in AS Mode (Serial Configuration Device Programmed by APU or Third-Party Programmer) (*Note 1*), (4)



#### Notes to Figure 3-3:

- (1) For the V<sub>CC</sub> value, refer to the respective FPGA family handbook Configuration chapter.
- (2) Serial configuration devices cannot be cascaded.
- (3) Connect the FPGA MSEL [] input pins to select the AS configuration mode. For details, refer to the respective FPGA family chapter in the *Configuration Handbook*.
- (4) For more information about configuration pin I/O requirements in an AS scheme for an Altera FPGA, refer to the respective FPGA family handbook Configuration chapter.

The FPGA acts as the configuration master in the configuration flow and provides the clock to the serial configuration device. The FPGA enables the serial configuration device by pulling the *n*CS signal low via the *n*CSO signal (refer to Figure 3–2 and Figure 3–3). Subsequently, the FPGA sends the instructions and addresses to the serial configuration device via the ASDO signal. The serial configuration device responds to the instructions by sending the configuration data to the FPGA's DATAO pin on the falling edge of DCLK. The data is latched into the FPGA on the next DCLK signal's falling edge.

Before the FPGA enters configuration mode, ensure that  $V_{CC}$  of the EPCS is ready. If it is not, you must hold *n*CONFIG low until all power rails of EPCS are ready.

The FPGA controls the *n*STATUS and CONF\_DONE pins during configuration in AS mode. If the CONF\_DONE signal does not go high at the end of configuration or if the signal goes high too early, the FPGA will pulse its *n*STATUS pin low to start reconfiguration. Upon successful configuration, the FPGA releases the CONF\_DONE pin, allowing the external 10-k $\Omega$  resistor to pull this signal high. Initialization begins after the CONF\_DONE goes high. After initialization, the FPGA enters user mode.

For more information about configuring the FPGAs in AS mode or other configuration modes, refer to the Configuration chapter in the appropriate device handbook. Multiple devices can be configured by a single EPCS device. However, serial configuration devices cannot be cascaded. Refer to Table 3–1 to ensure the programming file size of the cascaded FPGAs does not exceed the capacity of a serial configuration device. Figure 3–4 shows the AS configuration scheme with multiple FPGAs in the chain. The first FPGA is the configuration master and has its MSEL [] pins set to AS mode. The following FPGAs are configuration slave devices and have their MSEL [] pins set to PS mode.

Figure 3-4. Multiple Devices in AS Mode (Note 1), (5)



#### Notes to Figure 3-4:

- (1) For the V<sub>CC</sub> value, refer to the respective FPGA family handbook Configuration chapter.
- (2) Serial configuration devices cannot be cascaded.
- (3) Connect the FPGA MSEL [] input pins to select the AS configuration mode. For details, refer to the appropriate FPGA family chapter in the *Configuration Handbook.*
- (4) Connect the FPGA MSEL [] input pins to select the PS configuration mode. For details, refer to the appropriate FPGA family chapter in the *Configuration Handbook*.
- (5) For more information about configuration pin I/O requirements in an AS scheme for an Altera FPGA, refer to the respective FPGA family handbook Configuration chapter.

# **Serial Configuration Device Memory Access**

This section describes the serial configuration device's memory array organization and operation codes. Timing specifications for the memory are provided in the "Timing Information" section.

## **Memory Array Organization**

Table 3–2 provides details about the memory array organization in EPCS128, EPCS64, EPCS16, EPCS16, EPCS1, and EPCS1.

Details	EPCS128	EPCS64	EPCS16	EPCS4	EPCS1
Bytes (bits)	16,777,216 bytes (128 Mbits)	8,388,608 bytes (64 Mbits)	2,097,152 bytes (16 Mbits)	524,288 bytes (4 Mbits)	131,072 bytes (1 Mbit)
Number of sectors	64	128	32	8	4
Bytes (bits) per sector	262,144 bytes (2 Mbits)	65,536 bytes (512 Kbits)	65,536 bytes (512 Kbits)	65,536 bytes (512 Kbits)	32,768 bytes (256 Kbits)
Pages per sector	1,024	256	256	256	128
Total number of pages	65,536	32,768	8,192	2,048	512
Bytes per page	256 bytes	256 bytes	256 bytes	256 bytes	256 bytes

 Table 3–2.
 Memory Array Organization in Serial Configuration Devices

Table 3–3 through Table 3–7 list the address range for each sector in EPCS128, EPCS64, EPCS16, EPCS16, EPCS1, and EPCS1.

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
63	H'FC0000	H'FFFFFF	
62	H'F80000	H'FBFFFF	
61	H'F40000	H'F7FFFF	
60	H'F00000	H'F3FFFF	
59	H'EC0000	H'EFFFFF	
58	H'E80000	H'EBFFFF	
57	H'E40000	H'E7FFFF	
56	H'E00000	H'E3FFFF	
55	H'DC0000	H'DFFFFF	
54	H'D80000	H'DBFFFF	
53	H'D40000	H'D7FFFF	
52	H'D00000	H'D3FFFF	
51	Н'СС0000	H ' CFFFFF	
50	Н'С80000	H ' CBFFFF	
49	H'C40000	H'C7FFFF	
48	Н'С00000	H'C3FFFF	

Table 3–3. Address Range for Sectors in EPCS128 (Part 1 of 3)

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
47	H'BC0000	H'BFFFFF	
46	H'B80000	H'BBFFFF	
45	H'B40000	H'B7FFFF	
44	H'B00000	H'B3FFFF	
43	H'AC0000	H'AFFFFF	
42	H'A80000	H'ABFFFF	
41	H'A40000	H'A7FFFF	
40	H'A00000	H'A3FFFF	
39	Н'9С0000	H'9FFFFF	
38	H'980000	H'9BFFFF	
37	H'940000	H'97FFFF	
36	H'900000	H'93FFFF	
35	H'8C0000	H'8FFFF	
34	H'880000	H'8BFFFF	
33	H'840000	H'87FFFF	
32	H'800000	H'83FFFF	
31	H'7C0000	H'7FFFF	
30	H'780000	H'7BFFFF	
29	H'740000	H'77FFFF	
28	H'700000	H'73FFFF	
27	H'6C0000	H'6FFFF	
26	H'680000	H'6BFFFF	
25	H'640000	H'67FFFF	
24	H'600000	H'63FFFF	
23	H'5C0000	H'5FFFF	
22	H'580000	H'5BFFFF	
21	H'540000	H'57FFFF	
20	H'500000	H'53FFFF	
19	H'4C0000	H'4FFFFF	
18	H'480000	H'4BFFFF	
17	H'440000	H'47FFFF	
16	H'400000	H'43FFFF	
15	H'3C0000	H'3FFFFF	
14	H'380000	H'3BFFFF	
13	H'340000	H'37FFFF	
12	H'300000	H'33FFFF	
11	H'2C0000	H'2FFFF	
10	H'280000	H'2BFFFF	

Table 3-3. Address Range for Sectors in EPCS128 (Part 2 of 3)

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
9	H'240000	H'27FFFF	
8	H'200000	H'23FFFF	
7	H'1C0000	H'1FFFFF	
6	H'180000	H'1BFFFF	
5	H'140000	H'17FFFF	
4	H'100000	H'13FFFF	
3	H'0C0000	H'OFFFFF	
2	Н'080000	H'OBFFFF	
1	H'040000	H'07FFFF	
0	Н'000000	H'03FFFF	

Table 3-3. Address Range for Sectors in EPCS128 (Part 3 of 3)

 Table 3-4.
 Address Range for Sectors in EPCS64 (Part 1 of 4)

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
127	H'7F0000	H'7FFFF	
126	H'7E0000	H'7EFFFF	
125	H'7D0000	H'7DFFFF	
124	H'7C0000	H'7CFFFF	
123	H'7B0000	H'7BFFFF	
122	H'7A0000	H'7AFFFF	
121	H'790000	H'79FFFF	
120	H'780000	H'78FFFF	
119	H'770000	H'77FFFF	
118	H'760000	H'76FFFF	
117	H'750000	H'75FFFF	
116	H'740000	H'74FFFF	
115	H'730000	H'73FFFF	
114	H'720000	H'72FFFF	
113	H'710000	H'71FFFF	
112	H'700000	H'70FFFF	
111	H'6F0000	H'6FFFF	
110	H'6E0000	H'6EFFFF	
109	H'6D0000	H'6DFFFF	
108	H'6C0000	H'6CFFFF	
107	H'6B0000	H'6BFFFF	
106	H'6A0000	H'6AFFFF	
105	H'690000	H'69FFFF	
104	Н'680000	H'68FFFF	

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
103	H'670000	H'67FFFF	
102	H'660000	H'66FFFF	
101	H'650000	H'65FFFF	
100	H'640000	H'64FFFF	
99	H'630000	H'63FFFF	
98	H'620000	H'62FFFF	
97	H'610000	H'61FFFF	
96	Н'600000	H'60FFFF	
95	H'5F0000	H'5FFFFF	
94	H'5E0000	H'5EFFFF	
93	H'5D0000	H'5DFFFF	
92	H'5C0000	H'5CFFFF	
91	H'5B0000	H'5BFFFF	
90	H'5A0000	H'5AFFFF	
89	H'590000	H'59FFFF	
88	H'580000	H'58FFFF	
87	H'570000	H'57FFFF	
86	H'560000	H'56FFFF	
85	H'550000	H'55FFFF	
84	H'540000	H'54FFFF	
83	H'530000	H'53FFFF	
82	H'520000	H'52FFFF	
81	H'510000	H'51FFFF	
80	H'500000	H'50FFFF	
79	H'4F0000	H'4FFFFF	
78	H'4E0000	H'4EFFFF	
77	H'4D0000	H'4DFFFF	
76	H'4C0000	H'4CFFFF	
75	H'4B0000	H'4BFFFF	
74	H'4A0000	H'4AFFFF	
73	H'490000	H'49FFFF	
72	H'480000	H'48FFFF	
71	H'470000	H'47FFFF	
70	H'460000	H'46FFFF	
69	H'450000	H'45FFFF	
68	H'440000	H'44FFFF	
67	H'430000	H'43FFFF	
66	H'420000	H'42FFFF	

Table 3-4. Address Range for Sectors in EPCS64 (Part 2 of 4)

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
65	H'410000	H'41FFFF	
64	H'400000	H'40FFFF	
63	H'3F0000	H'3FFFFF	
62	H'3E0000	H'3EFFFF	
61	H'3D0000	H'3DFFFF	
60	H'3C0000	H'3CFFFF	
59	H'3B0000	H'3BFFFF	
58	H'3A0000	H'3AFFFF	
57	H'390000	H'39FFFF	
56	H'380000	H'38FFFF	
55	H'370000	H'37FFFF	
54	H'360000	H'36FFFF	
53	H'350000	H'35FFFF	
52	H'340000	H'34FFFF	
51	H'330000	H'33FFFF	
50	H'320000	H'32FFFF	
49	H'310000	H'31FFFF	
48	H'300000	H'30FFFF	
47	H'2F0000	H'2FFFF	
46	H'2E0000	H'2EFFFF	
45	H'2D0000	H'2DFFFF	
44	H'2C0000	H'2CFFFF	
43	H'2B0000	H'2BFFFF	
42	H'2A0000	H'2AFFFF	
41	H'290000	H'29FFFF	
40	H'280000	H'28FFFF	
39	H'270000	H'27FFFF	
38	H'260000	H'26FFFF	
37	H'250000	H'25FFFF	
36	H'240000	H'24FFFF	
35	H'230000	H'23FFFF	
34	H'220000	H'22FFFF	
33	H'210000	H'21FFFF	
32	H'200000	H'20FFFF	
31	H'1F0000	H'1FFFFF	
30	H'1E0000	H'1EFFFF	
29	H'1D0000	H'1DFFFF	
28	H'1C0000	H'1CFFFF	

**Table 3–4.** Address Range for Sectors in EPCS64 (Part 3 of 4)

	Address Range (Byt	e Addresses in HEX)
Sector	Start	End
27	H'1B0000	H'1BFFFF
26	H'1A0000	H'1AFFFF
25	H'190000	H'19FFFF
24	H'180000	H'18FFFF
23	H'170000	H'17FFFF
22	H'160000	H'16FFFF
21	H'150000	H'15FFFF
20	H'140000	H'14FFFF
19	H'130000	H'13FFFF
18	H'120000	H'12FFFF
17	H'110000	H'11FFFF
16	H'100000	H'10FFFF
15	H'0F0000	H'OFFFF
14	H'0E0000	H'OEFFFF
13	H'0D0000	H'ODFFFF
12	H'0C0000	H'OCFFFF
11	Н'0В0000	H'OBFFFF
10	H'0A0000	H'OAFFFF
9	H'090000	H'09FFFF
8	Н'080000	H'08FFFF
7	H'070000	H'07FFFF
6	H'060000	H'06FFFF
5	Н'050000	H'05FFFF
4	H'040000	H'04FFFF
3	H'030000	H'03FFFF
2	H'020000	H'02FFFF
1	H'010000	H'01FFFF
0	Н'000000	H'OOFFFF

 Table 3–4.
 Address Range for Sectors in EPCS64 (Part 4 of 4)

**Table 3–5.** Address Range for Sectors in EPCS16 (Part 1 of 2)

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
31	H'1F0000	H'1FFFFF	
30	H'1E0000	H'1EFFFF	
29	H'1D0000	H'1DFFFF	
28	H'1C0000	H'1CFFFF	
27	H'1B0000	H'1BFFFF	
26	H'1A0000	H'1AFFFF	

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
25	H'190000	H'19FFFF	
24	H'180000	H'18FFFF	
23	H'170000	H'17FFFF	
22	H'160000	H'16FFFF	
21	H'150000	H'15FFFF	
20	H'140000	H'14FFFF	
19	H'130000	H'13FFFF	
18	H'120000	H'12FFFF	
17	H'110000	H'11FFFF	
16	H'100000	H'10FFFF	
15	H'0F0000	H'OFFFF	
14	H'0E0000	H'OEFFFF	
13	H'0D0000	H'ODFFFF	
12	H'0C0000	H'OCFFFF	
11	H'0B0000	H'OBFFFF	
10	H'0A0000	H'OAFFFF	
9	H'090000	H'09FFFF	
8	H'080000	H'08FFFF	
7	H'070000	H'07FFFF	
6	H'060000	H'06FFFF	
5	H'050000	H'05FFFF	
4	H'040000	H'04FFFF	
3	H'030000	H'03FFFF	
2	H'020000	H'02FFFF	
1	H'010000	H'01FFFF	
0	Н'00000	H'OOFFFF	

 Table 3–5.
 Address Range for Sectors in EPCS16 (Part 2 of 2)

**Table 3–6.** Address Range for Sectors in EPCS4 (Part 1 of 2)

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
7	H'70000	H'7FFFF	
6	Н'60000	H'6FFFF	
5	Н'50000	H'5FFFF	
4	H'40000	H'4FFFF	
3	Н'30000	H'3FFFF	
2	H'20000	H'2FFFF	

	Address Range (Byte Addresses in HEX)		
Sector	Start	End	
1	H'10000	H'1FFFF	
0	Н'00000	H'OFFFF	

#### Table 3–6. Address Range for Sectors in EPCS4 (Part 2 of 2)

Table 3–7. Address Range for Sectors in EPCS1

	Address Range (Byte Addresses in HEX)			
Sector	Start	End		
3	H'18000	H'1FFFF		
2	H'10000	H'17FFF		
1	H'08000	H'OFFFF		
0	H'00000	H'07FFF		

## **Operation Codes**

This section describes the operations that can be used to access the memory in serial configuration devices. The DATA, DCLK, ASDI, and *n*CS signals access the memory in serial configuration devices. All serial configuration device operation codes, addresses and data are shifted in and out of the device serially, with the most significant bit (MSB) first.

The device samples the active serial data input on the first rising edge of the DCLK after the active low chip select (nCS) input signal is driven low. Shift the operation code (MSB first) serially into the serial configuration device through the active serial data input (ASDI) pin. Each operation code bit is latched into the serial configuration device on the rising edge of the DCLK.

Different operations require a different sequence of inputs. While executing an operation, you must shift in the desired operation code, followed by the address bytes, data bytes, both, or neither. The device must drive *n*CS high after the last bit of the operation sequence is shifted in. Table 3–8 lists the operation sequence for every operation supported by the serial configuration devices.

For the read byte, read status, and read silicon ID operations, the shifted-in operation sequence is followed by data shifted out on the DATA pin. You can drive the *n*CS pin high after any bit of the data-out sequence is shifted out.

For the write byte, erase bulk, erase sector, write enable, write disable, and write status operations, drive the *n*CS pin high exactly at a byte boundary (drive the *n*CS pin high a multiple of eight clock pulses after the *n*CS pin is driven low); otherwise, the operation is rejected and is not executed.

All attempts to access the memory contents while a write or erase cycle is in progress will not be granted, and the write or erase cycle will continue unaffected.

Operation	Operation Code (1)	Address Bytes	Dummy Bytes	Data Bytes	DCLK f <sub>max</sub> (MHz)
Write enable	0000 0110	0	0	0	25
Write disable	0000 0100	0	0	0	25
Read status	0000 0101	0	0	1 to infinite (2)	25
Read bytes	0000 0011	3	0	1 to infinite (2)	20
Read silicon ID (4)	1010 1011	0	3	1 to infinite (2)	25
Fast read	0000 1011	3	1	1 to infinite (2)	40
Write status	0000 0001	0	0	1	25
Write bytes	0000 0010	3	0	1 to 256 <i>(3)</i>	25
Erase bulk	1100 0111	0	0	0	25
Erase sector	1101 1000	3	0	0	25
Read Device Identification (5)	1001 1111	0	2	1 to infinite (2)	25

Table 3–8	Operation Codes for Serial Configuration Devices
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Notes to Table 3-8:

(1) The MSB is listed first and the least significant bit (LSB) is listed last.

(2) The status register, data or silicon ID are read out at least once on the DATA pin and will continuously be read out until nCs is driven high.

(3) Write bytes operation requires at least one data byte on the DATA pin. If more than 256 bytes are sent to the device, only the last 256 bytes are written to the memory.

(4) Read silicon ID operation is available only for EPCS1, EPCS4, EPCS16, and EPCS64.

(5) Read Device Identification operation is available only for EPCS128.

### Write Enable Operation

The write enable operation code is b'0000 0110, and the MSB is listed first. The write enable operation sets the write enable latch bit, which is bit 1 in the status register. Always set the write enable latch bit before write bytes, write status, erase bulk, and erase sector operations. Figure 3–5 shows the timing diagram for the write enable operation. Figure 3–7 and Figure 3–8 show the status register bit definitions.

Figure 3–5. Write Enable Operation Timing Diagram



## Write Disable Operation

The write disable operation code is b'0000 0100, with the MSB listed first. The write disable operation resets the write enable latch bit, which is bit 1 in the status register. To prevent the memory from being written unintentionally, the write enable latch bit is automatically reset when implementing the write disable operation as well as under the following conditions:

- Power up
- Write bytes operation completion
- Write status operation completion
- Erase bulk operation completion
- Erase sector operation completion

Figure 3–6 shows the timing diagram for the write disable operation.





## **Read Status Operation**

The read status operation code is b'0000 0101, with the MSB listed first. You can use the read status operation to read the status register. Figure 3–7 and Figure 3–8 show the status bits in the status register of the serial configuration devices.

Figure 3–7. EPCS4, EPCS16, EPCS64, and EPCS128 Status Register Status Bits



## Figure 3-8. EPCS1 Status Register Status Bits



Setting the write in progress bit to 1 indicates that the serial configuration device is busy with a write or erase cycle. Resetting the write in progress bit to 0 means no write or erase cycle is in progress.

Resetting the write enable latch bit to 0 indicates that no write or erase cycle will be accepted. Set the write enable latch bit to 1 before every write bytes, write status, erase bulk, and erase sector operation.

The non-volatile block protect bits determine the area of the memory protected from being written or erased unintentionally. Table 3–9 through Table 3–13 list the protected area in the serial configuration devices with reference to the block protect bits. The erase bulk operation is only available when all the block protect bits are 0. When any of the block protect bits are set to 1, the relevant area is protected from being written by write bytes operations or erased by erase sector operations.

Status Register Content		Memory Content		
BP1 Bit	BPO Bit	Protected Area	Unprotected Area	
0	0	None	All four sectors: 0 to 3	
0	1	Sector 3	Three sectors: 0 to 2	
1	0	Two sectors: 2 and 3	Two sectors: 0 and 1	
1	1	All sectors	None	

Table 3–9. Block Protection Bits in EPCS1

Table 3-10.	Block Protection	Bits in EPCS4
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Statu	ıs Register Co	ntent	Memory Content	
BP2 Bit BP1 Bit BP0 Bit			Protected Area	Unprotected Area
0	0	0	None	All eight sectors: 0 to 7
0	0	1	Sector 7	Seven sectors: 0 to 6
0	1	0	Sectors 6 and 7	Six sectors: 0 to 5
0	1	1	Four sectors: 4 to 7	Four sectors: 0 to 3
1	0	0	All sectors	None
1	0	1	All sectors	None
1	1	0	All sectors	None
1	1	1	All sectors	None

 Table 3–11.
 Block Protection Bits in EPCS16 (Part 1 of 2)

	tus Regi Content			nory Content
BP2 Bit	BP1 Bit	BPO Bit	Protected Area	Unprotected Area
0	0	0	None	All sectors (32 sectors 0 to 31)
0	0	1	Upper 32nd (Sector 31)	Lower 31/32nds (31 sectors: 0 to 30)
0	1	0	Upper sixteenth (two sectors: 30 and 31)	Lower 15/16ths (30 sectors: 0 to 29)
0	1	1	Upper eighth (four sectors: 28 to 31)	Lower seven-eighths (28 sectors: 0 to 27)
1	0	0	Upper quarter (eight sectors: 24 to 31)	Lower three-quarters (24 sectors: 0 to 23)
1	0	1	Upper half (sixteen sectors: 16 to 31)	Lower half (16 sectors: 0 to 15)

	Status Register Content Memory Content		Content		
BP2 Bit	BP1 Bit	BPO Bit	Protected Area Unprotected Area		
1	1	0	All sectors (32 sectors: 0 to 31)	None	
1	1	1	All sectors (32 sectors: 0 to 31)	None	

### Table 3–11. Block Protection Bits in EPCS16 (Part 2 of 2)

## Table 3–12. Block Protection Bits in EPCS64

	Status Register Content		Memory Content		
BP2 Bit	BP1 Bit	BPO Bit	Protected Area	Unprotected Area	
0	0	0	None	All sectors (128 sectors: 0 to 127)	
0	0	1	Upper 64th (2 sectors: 126 and 127)	Lower 63/64ths (126 sectors: 0 to 125)	
0	1	0	Upper 32nd (4 sectors: 124 to 127)	Lower 31/32nds (124 sectors: 0 to 123)	
0	1	1	Upper sixteenth (8 sectors: 120 to 127)	Lower 15/16ths (120 sectors: 0 to 119)	
1	0	0	Upper eighth (16 sectors: 112 to 127)	Lower seven-eighths (112 sectors: 0 to 111)	
1	0	1	Upper quarter (32 sectors: 96 to 127)	Lower three-quarters (96 sectors: 0 to 95)	
1	1	0	Upper half (64 sectors: 64 to 127)	Lower half (64 sectors: 0 to 63)	
1	1	1	All sectors (128 sectors: 0 to 127)	None	

## Table 3–13. Block Protection Bits in EPCS128

	tus Regi Content		Memory Content	
BP2 Bit	BP1 Bit	BPO Bit	Protected Area	Unprotected Area
0	0	0	None	All sectors (64 sectors: 0 to 63)
0	0	1	Upper 64th (1 sector: 63)	Lower 63/64ths (63 sectors: 0 to 62)
0	1	0	Upper 32nd (2 sectors: 62 to 63)	Lower 31/32nds (62 sectors: 0 to 61)
0	1	1	Upper 16th (4 sectors: 60 to 63)	Lower 15/16ths (60 sectors: 0 to 59)
1	0	0	Upper 8th (8 sectors: 56 to 63)	Lower seven-eighths (56 sectors: 0 to 55)
1	0	1	Upper quarter (16 sectors: 48 to 63)	Lower three-quarters (48 sectors: 0 to 47)
1	1	0	Upper half (32 sectors: 32 to 63)	Lower half (32 sectors: 0 to 31)
1	1	1	All sectors (64 sectors: 0 to 63)	None

You can read the status register at any time, even while a write or erase cycle is in progress. When one of these cycles is in progress, you can check the write in progress bit (bit 0 of the status register) before sending a new operation to the device. The device can also read the status register continuously, as shown in Figure 3–9.





## Write Status Operation

The write status operation code is b'0000 0001, with the MSB listed first. Use the write status operation to set the status register block protection bits. The write status operation has no effect on the other bits. Therefore, you can implement this operation to protect certain memory sectors, as defined in Table 3–9 through Table 3–13. After setting the block protect bits, the protected memory sectors are treated as read-only memory. You must execute the write enable operation before the write status operation so the device sets the status register's write enable latch bit to 1.

The write status operation is implemented by driving *n*CS low, followed by shifting in the write status operation code and one data byte for the status register on the ASDI pin. Figure 3–10 shows the timing diagram for the write status operation. *n*CS must be driven high after the eighth bit of the data byte has been latched in, otherwise, the write status operation is not executed.

Immediately after *n*CS drives high, the device initiates the self-timed write status cycle. The self-timed write status cycle usually takes 5 ms for all serial configuration devices and is guaranteed to be less than 15 ms (refer to  $t_{WS}$  in Table 3–16). You must account for this delay to ensure that the status register is written with desired block protect bits. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the self-timed write status cycle is in progress. The write in progress bit is 1 during the self-timed write status cycle, and 0 when it is complete.

Figure 3–10. Write Status Operation Timing Diagram



## **Read Bytes Operation**

The read bytes operation code is b'0000 0011, with the MSB listed first. To read the memory contents of the serial configuration device, the device is first selected by driving *n*CS low. Then, the read bytes operation code is shifted in followed by a 3-byte address (A[23..0]). Each address bit must be latched in on the rising edge of the DCLK. After the address is latched in, the memory contents of the specified address are shifted out serially on the DATA pin, beginning with the MSB. For reading Raw Programming Data files (**.rpd**), the content is shifted out serially beginning with the LSB. Each data bit is shifted out on the falling edge of DCLK. The maximum DCLK frequency during the read bytes operation is 20 MHz. Figure 3–11 shows the timing diagram for the read bytes operation.

The first byte address can be at any location. The device automatically increments the address to the next higher address after shifting out each byte of data. Therefore, the device can read the whole memory with a single read bytes operation. When the device reaches the highest address, the address counter restarts at  $0 \times 000000$ , allowing the memory contents to be read out indefinitely until the read bytes operation is terminated by driving *n*CS high. The device can drive *n*CS high any time after data is shifted out. If the read bytes operation is shifted in while a write or erase cycle is in progress, the operation is not executed and has no effect on the write or erase cycle in progress.

Figure 3–11. Read Bytes Operation Timing Diagram



### Notes to Figure 3-11:

- (1) Address bit A [23] is a don't-care bit in EPCS64. Address bits A [23..21] are don't-care bits in EPCS16. Address bits A [23..19] are don't-care bits in EPCS4. Address bits A [23..19] are don't-care bits in the EPCS1.
- (2) For .rpd files, the read sequence shifts out the LSB of the data byte first.

## **Fast Read Operation**

The device is first selected by driving *n*CS low. The fast read instruction code is followed by a 3-byte address (A23-A0) and a dummy byte, each bit being latched-in during the rising edge of DCLK. Then the memory contents, at that address, is shifted out on DATA, each bit being shifted out, at a maximum frequency of 40 MHz, during the falling edge of DCLK.

The instruction sequence is shown in Figure 3–12.

The first byte addressed can be at any location. The address is automatically incremented to the next higher address after each byte of data is shifted out. The whole memory can, therefore, be read with a single fast read instruction. When the highest address is reached, the address counter rolls over to 000000h, allowing the read sequence to be continued indefinitely.

The fast read instruction is terminated by driving nCS high at any time during data output. Any fast read instruction is rejected during the Erase, Program, or Write operations without any effect on the operation that is in progress .



Figure 3–12. FAST\_READ Operation Timing Diagram

#### Note to Figure 3–12:

(1) Address bit A [23] is a don't-care bit in EPCS64. Address bits A [23..21] are don't-care bits in EPCS16. Address bits A [23..19] are don't-care bits in EPCS4. Address bits A [23..17] are don't-care bits in the EPCS1.

## **Read Silicon ID Operation**

The read silicon ID operation code is b'1010 1011, with the MSB listed first. Only EPCS1, EPCS4, EPCS16, and EPCS64 support this operation. It reads the serial configuration device's 8-bit silicon ID from the DATA output pin. If this operation is shifted in during an erase or write cycle, it is ignored and has no effect on the cycle that is in progress.

Table 3-14 lists the serial configuration device silicon IDs.

Table 3-14.	Serial	Configuration	Device	Silicon	ID
-------------	--------	---------------	--------	---------	----

Serial Configuration Device	Silicon ID (Binary Value)
EPCS1	b'0001 0000
EPCS4	b'0001 0010
EPCS16	b'0001 0100
EPCS64	b'0001 0110

The device implements the read silicon ID operation by driving *n*CS low then shifting in the read silicon ID operation code followed by three dummy bytes on ASDI. The serial configuration device's 8-bit silicon ID is then shifted out on the DATA pin on the falling edge of DCLK, as shown in Figure 3–13. The device can terminate the read silicon ID operation by driving *n*CS high after the silicon ID has been read at least once. Sending additional clock cycles on DCLK while *n*CS is driven low can cause the silicon ID to be shifted out repeatedly.

Figure 3–13. Read Silicon ID Operation Timing Diagram (Note 1)



### Note to Figure 3-13:

(1) Only EPCS1, EPCS4, EPCS16, and EPCS64 support Read Silicon ID operation.

### **Read Device Identification Operation**

The read device identification operation code is b'1001 1111, with the MSB listed first. Only EPCS128 supports this operation. It reads the serial configuration device's 8-bit device identification from the DATA output pin. If this operation is shifted in during an erase or write cycle, it is ignored and has no effect on the cycle that is in progress. Table 3–15 shows the serial configuration device identification.

 Table 3–15.
 Serial Configuration Device Identification

Serial Configuration Device	Silicon ID (Binary Value)
EPCS128	b'0001 1000

The device implements the read device identification operation by driving *n*CS low then shifting in the read device identification operation code followed by two dummy byte on ASDI. The serial configuration device's 16-bit device identification is then shifted out on the DATA pin on the falling edge of DCLK, as shown in Figure 3–14. The device can terminate the read device identification operation by driving *n*CS high after reading the device identification at least once.

Figure 3–14. Read Device Identification Operation Timing Diagram (Note 1)



#### Note to Figure 3-14:

(1) Only EPCS128 supports read device identification operation.

### Write Bytes Operation

The write bytes operation code is b'0000 0010, with the MSB listed first. The write bytes operation allows bytes to be written to the memory. The write enable operation must be executed prior to the write bytes operation to set the write enable latch bit in the status register to 1.

The write bytes operation is implemented by driving *n*CS low, followed by the write bytes operation code, three address bytes and a minimum one data byte on ASDI. If the eight least significant address bits (A[7..0]) are not all 0, all sent data that goes beyond the end of the current page is not written into the next page. Instead, this data is written at the start address of the same page (from the address whose eight LSBs are all 0). Drive *n*CS low during the entire write bytes operation sequence, as shown in Figure 3–15.

If more than 256 data bytes are shifted into the serial configuration device with a write bytes operation, the previously latched data is discarded and the last 256 bytes are written to the page. However, if less than 256 data bytes are shifted into the serial configuration device, they are guaranteed to be written at the specified addresses and the other bytes of the same page are unaffected.

If the design must write more than 256 data bytes to the memory, it needs more than one page of memory. Send the write enable and write bytes operation codes followed by three new targeted address bytes and 256 data bytes before a new page is written.

nCS must be driven high after the eighth bit of the last data byte has been latched in. Otherwise, the device will not execute the write bytes operation. The write enable latch bit in the status register is reset to 0 before the completion of each write bytes operation. Therefore, the write enable operation must be carried out before the next write bytes operation.

The device initiates the self-timed write cycle immediately after *n*CS is driven high. Refer to  $t_{WB}$  in Table 3–16 on page 3–27 for the self-timed write cycle time for the respective EPCS devices. Therefore, you must account for this amount of delay before another page of memory is written. Alternatively, you can check the status register's write in progress bit by executing the read status operation while the self-timed write cycle is in progress. The write in progress bit is set to 1 during the self-timed write cycle, and 0 when it is complete.

The bytes of serial configuration devices memory must be erased to all 1 or 0xFF before write bytes operation is implemented. This can be achieved by either using the erase sector instruction in a sector, or the erase bulk instruction throughout the entire memory.

Figure 3–15. Write Bytes Operation Timing Diagram (Note 1)



#### Notes to Figure 3–15:

- (1) Use the erase sector or the erase bulk instruction to initialize the memory bytes of the serial configuration devices to all 1 or 0xFF before implementing the write bytes operation.
- (2) Address bit A [23] is a don't-care bit in EPCS64. Address bits A [23..21] are don't-care bits in EPCS16. Address bits A [23..19] are don't-care bits in EPCS1. Address bits A [23..17] are don't-care bits in EPCS1.
- (3) For .rpd files, write the LSB of the data byte first.

### **Erase Bulk Operation**

The erase bulk operation code is b'1100~0111, with the MSB listed first. The erase bulk operation sets all memory bits to 1 or 0xFF. Similar to the write bytes operation, the write enable operation must be executed prior to the erase bulk operation so that the write enable latch bit in the status register is set to 1.

You can implement the erase bulk operation by driving *n*CS low and then shifting in the erase bulk operation code on the ASDI pin. *n*CS must be driven high after the eighth bit of the erase bulk operation code has been latched in. Figure 3–16 shows the timing diagram.

The device initiates the self-timed erase bulk cycle immediately after *n*CS is driven high. Refer to  $t_{EB}$  in Table 3–16 for the self-timed erase bulk cycle time for the respective EPCS devices.

You must account for this delay before accessing the memory contents. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the self-timed erase cycle is in progress. The write in progress bit is 1 during the self-timed erase cycle and 0 when it is complete. The write enable latch bit in the status register is reset to 0 before the erase cycle is complete.





### **Erase Sector Operation**

The erase sector operation code is b'1101 1000, with the MSB listed first. The erase sector operation allows the user to erase a certain sector in the serial configuration device by setting all bits inside the sector to 1 or 0xFF. This operation is useful for users who access the unused sectors as general purpose memory in their applications.

The write enable operation must be executed prior to the erase sector operation so that the write enable latch bit in the status register is set to 1.

The erase sector operation is implemented by first driving *n*CS low, then shifting in the erase sector operation code and the three address bytes of the chosen sector on the ASDI pin. The three address bytes for the erase sector operation can be any address inside the specified sector. (Refer to Table 3–3 through Table 3–7 for sector address range information.) Drive *n*CS high after the eighth bit of the erase sector operation code has been latched in. Figure 3–17 shows the timing diagram.

Immediately after the device drives *n*CS high, the self-timed erase sector cycle is initiated. Refer to  $t_{ES}$  in Table 3–16 for the self-timed erase sector cycle time for the respective EPCS devices. You must account for this amount of delay before the memory contents can be accessed. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the erase cycle is in progress. The write in progress bit is 1 during the self-timed erase cycle and 0 when it is complete. The write enable latch bit in the status register resets to 0 before the erase cycle is complete.





#### Note to Figure 3-17:

(1) Address bit A [23] is a don't-care bit in EPCS64. Address bits A [23..21] are don't-care bits in EPCS16. Address bits A [23..19] are don't-care bits in EPCS4. Address bits A [23..17] are don't-care bits in EPCS1.

# **Power and Operation**

This section describes the power modes, power-on reset (POR) delay, error detection, and initial programming state of serial configuration devices.

# **Power Mode**

Serial configuration devices support active power and standby power modes. When *n*CS is low, the device is enabled and is in active power mode. The FPGA is configured while in active power mode. When *n*CS is high, the device is disabled but could remain in active power mode until all internal cycles have completed (such as write or erase operations). The serial configuration device then goes into stand-by power mode. The I<sub>CC1</sub> parameter specifies the V<sub>CC</sub> supply current when the device is in active power mode and the I<sub>CC0</sub> parameter specifies the current when the device is in stand-by power mode (refer to Table 3–21).

# **Power-On Reset**

During initial power-up, a POR delay occurs to ensure the system voltage levels have stabilized. During AS configuration, the FPGA controls the configuration and has a longer POR delay than the serial configuration device.



For the POR delay time, refer to the configuration chapter in the appropriate device handbook.

# **Error Detection**

During AS configuration with the serial configuration device, the FPGA monitors the configuration status through the *n*STATUS and CONF\_DONE pins. If an error condition occurs (*n*STATUS drives low) or if the CONF\_DONE pin does not go high, the FPGA will begin reconfiguration by pulsing the *n*STATUS and *n*CSO signals, which controls the chip select pin on the serial configuration device (*n*CS).

After an error, configuration automatically restarts if the **Auto-Restart Upon Frame Error** option is turned on in the Quartus<sup>®</sup> II software. If the option is turned off, the system must monitor the *n*STATUS signal for errors and then pulse the *n*CONFIG signal low to restart configuration.

# **Timing Information**

Figure 3–18 shows the timing waveform for write operation to the serial configuration device.

### Figure 3–18. Write Operation Timing



Table 3–16 defines the serial configuration device timing parameters for write operation.

Table 3–16. Write Operation Parameters

Symbol	Parameter	Min	Тур	Max	Unit
f <sub>wclk</sub>	Write clock frequency (from FPGA, download cable, or embedded processor) for write enable, write disable, read status, read silicon ID, write bytes, erase bulk, and erase sector operations		_	25	MHz
t <sub>CH</sub>	DCLK high time	20	—	—	ns
t <sub>CL</sub>	DCLK low time	20	—	—	ns
t <sub>NCSSU</sub>	Chip select (nCS) setup time	10	—	—	ns
t <sub>NCSH</sub>	Chip select (nCS) hold time	10	—	—	ns
t <sub>DSU</sub>	Data (ASDI) in setup time before rising edge on DCLK	5	—	—	ns
t <sub>DH</sub>	Data (ASDI) hold time after rising edge on DCLK	5	_	_	ns
t <sub>CSH</sub>	Chip select high time	100	—	_	ns
t <sub>WB</sub> (1)	Write bytes cycle time for EPCS1, EPCS4, EPCS16, and EPCS64		1.5	5	ms
	Write bytes cycle time for EPCS128		2.5	7	ms
t <sub>WS</sub> (1)	Write status cycle time		5	15	ms
t <sub>EB</sub> (1)	Erase bulk cycle time for EPCS1		3	6	S
	Erase bulk cycle time for EPCS4		5	10	S
	Erase bulk cycle time for EPCS16		17	40	S
	Erase bulk cycle time for EPCS64	—	68	160	S
	Erase bulk cycle time for EPCS128	_	105	250	S
t <sub>ES</sub> (1)	Erase sector cycle time for EPCS1, EPCS4, EPCS16, and EPCS64		2	3	S
	Erase sector cycle time for EPCS128	_	2	6	S

Note to Table 3-16:

(1) These parameters are not shown in Figure 3–18.

Figure 3–19 shows the timing waveform for the serial configuration device's read operation.

Figure 3–19. Read Operation Timing



Table 3–17 defines the serial configuration device timing parameters for read operation.

 Table 3–17.
 Read Operation Parameters

Symbol Parameter		Min	Max	Unit
f <sub>rclk</sub>	Read clock frequency (from FPGA or embedded processor) for read bytes operation	_	20	MHz
t <sub>CH</sub>	DCLK high time	25	_	ns
t <sub>CL</sub>	DCLK low time	25	_	ns
t <sub>odis</sub>	Output disable time after read	—	15	ns
t <sub>nCLK2D</sub>	Clock falling edge to data	—	8	ns

Existing batches of EPCS1 and EPCS4 manufactured on 0.15 µm process geometry support AS configuration up to 40 MHz. However, batches of EPCS1 and EPCS4 manufactured on 0.18 µm process geometry support only up to 20 MHz. EPCS16, EPCS64, and EPCS128 are not affected.

For information about product traceability and transition date to differentiate between 0.15 μm process geometry and 0.18 μm process geometry EPCS1 and EPCS4, refer to the Process Change Notification *PCN 0514: Manufacturing Changes on EPCS Family.* 

Figure 3–20 shows the timing waveform for FPGA AS configuration scheme using a serial configuration device.

Figure 3–20. AS Configuration Timing



### Note to Figure 3-20:

(1) t<sub>CD2UM</sub> is a FPGA dependent parameter. For more information, refer to the respective device configuration chapters.

•••

For more information about the timing parameters in Figure 3–20, refer to the respective FPGA family handbook Configuration chapter.

# **Programming and Configuration File Support**

The Quartus II software provides programming support for serial configuration devices. After selecting the serial configuration device, the Quartus II software automatically generates the Programmer Object File (**.pof**) to program the device. The software allows users to select the appropriate serial configuration device density that most efficiently stores the configuration data for a selected FPGA.

The serial configuration device can be programmed in-system by an external microprocessor using SRunner. SRunner is a software driver developed for embedded serial configuration device programming that you can customize to fit in different embedded systems. The SRunner can read **.rpd** files and write to the serial configuration devices. The programming time is comparable to the Quartus II software programming time. Note that writing and reading the **.rpd** file to the EPCS is different from other data and address bytes. The LSB of **.rpd** bytes must be shifted out first during the read bytes instruction and the LSB of **.rpd** bytes must be shifted in first during the write bytes instruction. This is because the FPGA reads the LSB of the **.rpd** data first during the configuration process.

For more information about SRunner, refer to *AN* 418: *SRunner: An Embedded Solution for Serial Configuration Device Programming User Guide* and the source code on the Altera website (www.altera.com).

Serial configuration devices can be programmed using the APU with the appropriate programming adapter (PLMSEPC-8) via the Quartus II software, USB Blaster, EthernetBlaster, or the ByteBlaster II download cable via the Quartus II software. In addition, many third-party programmers, such as BP Microsystems and System General, offer programming hardware that supports serial configuration devices.

During in-system programming of a serial configuration device via the USB Blaster, EthernetBlaster, or ByteBlaster II download cable, the cable pulls *n*CONFIG low to reset the FPGA and overrides the 10-k $\Omega$  pull-down resistor on the FPGA's *n*CE pin (refer to Figure 3–2). The download cable then uses the four interface pins (DATA, *n*CS, ASDI, and DCLK) to program the serial configuration device. When the programming is complete, the download cable releases the serial configuration device's four interface pins and the FPGA's *n*CE pin, and pulses *n*CONFIG to start configuration.

The FPGA can program the serial configuration device in-system using the JTAG interface with the Serial FlashLoader. This solution allows you to indirectly program the serial configuration device using the same JTAG interface that is used to configure the FPGA.

For more information about the Serial FlashLoader, refer to *AN* 370: Using the Serial FlashLoader with the Quartus II Software.

• For more information about programming and configuration support, refer to the following documents:

- Altera Programming Hardware Data Sheet
- Programming Hardware Manufacturers
- USB-Blaster Download Cable User Guide
- ByteBlaster II Download Cable User Guide
- EthernetBlaster Communications Cable User Guide

# **Operating Conditions**

Table 3–18 through Table 3–22 provide information about absolute maximum ratings, recommended operating conditions, DC operating conditions, and capacitance for serial configuration devices.

 Table 3–18.
 Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Condition	Min	Max	Unit
V <sub>CC</sub>	Supply voltage for EPCS1, EPCS4, and EPCS16	With respect to ground	-0.6	4.0	V
	Supply voltage for EPCS64 and EPCS128	With respect to ground	-0.2	4.0	V
VI	DC input voltage for EPCS1, EPCS4, and EPCS16	With respect to ground	-0.6	4.0	V
	DC input voltage for EPCS64 and EPCS128	With respect to ground	-0.5	4.0	V
I <sub>MAX</sub>	DC V <sub>CC</sub> or GND current	_	—	15	mA
I <sub>OUT</sub>	DC output current per pin	—	-25	25	mA
P <sub>D</sub>	Power dissipation	—	—	54	mW
T <sub>STG</sub>	Storage temperature	No bias	-65	150	°C
T <sub>AMB</sub>	Ambient temperature	Under bias	-65	135	°C
TJ	Junction temperature	Under bias	—	135	°C

Table 3–19.	Recommended	Operating	Conditions
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Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply voltage	(2)	2.7	3.6	V
VI	Input voltage	Respect to GND	-0.3	0.3 + V <sub>CC</sub>	V
V <sub>0</sub>	Output voltage		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating temperature	For commercial use	0	70	°C
		For industrial use	-40	85	٥C
		For extended industrial temperature	-40	125	°C
t <sub>R</sub>	Input rise time		—	5	ns
t <sub>F</sub>	Input fall time		_	5	ns

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>IH</sub>	High-level input voltage for EPCS1, EPCS4, and EPCS16	_	0.6 x V <sub>CC</sub>	V <sub>CC</sub> + 0.4	V
	High-level input voltage for EPCS64 and EPCS128	_	0.6 x V <sub>CC</sub>	V <sub>CC</sub> + 0.2	V
V <sub>IL</sub>	Low-level input voltage	—	-0.5	$0.3 \times V_{CC}$	V
V <sub>OH</sub>	High-level output voltage	I <sub>0H</sub> = -100 μA (3)	$V_{CC} - 0.2$	—	V
V <sub>OL</sub>	Low-level output voltage	I <sub>0L</sub> = 1.6 mA (3)	—	0.4	V
I <sub>I</sub>	Input leakage current	$V_{I} = V_{CC} \text{ or } GND$	-10	10	μA
I <sub>OZ</sub>	Tri-state output off-state current	$V_0 = V_{CC}$ or GND	-10	10	μA

Table 3-20.	DC Operating	Conditions
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## Table 3–21. Icc Supply Current

Symbol	Parameter	Conditions	Min	Max	Unit
I <sub>CC0</sub>	V <sub>CC</sub> supply current (standby)	—	_	50	μA
	for EPCS1, EPCS4, and EPCS16				
	V <sub>CC</sub> supply current (standby)	—		100	μΑ
	for EPCS64 and EPCS128				
I <sub>CC1</sub>	V <sub>CC</sub> supply current (during active power mode) for EPCS1, EPCS4, and EPCS16		5	15	mA
	V <sub>CC</sub> supply current (during active power mode) for EPCS64 and EPCS128		5	20	mA

### Table 3–22. Capacitance (Note 4)

Symbol	Parameter	Conditions	Min	Max	Unit
C <sub>IN</sub>	Input pin capacitance	$V_{IN} = 0 V$	_	6	рF
C <sub>OUT</sub>	Output pin capacitance	$V_{OUT} = 0 V$		8	pF

## Notes to Table 3–18 through Table 3–22:

(1) For more information, refer to the Operating Requirements for Altera Devices Data Sheet.

(2) Maximum  $V_{CC}$  rise time is 100 ms.

(3) The I<sub>OH</sub> parameter refers to high-level TTL or CMOS output current; the I<sub>OL</sub> parameter refers to low-level TTL or CMOS output current.

(4) Capacitance is sample-tested only at  $T_A = 25 \times C$  and at a 20-MHz frequency.

# **Pin Information**

As shown in Figure 3–21 and Figure 3–22, the serial configuration device is an 8-pin or 16-pin device. The control pins on the serial configuration device are: serial data output (DATA), active serial data input (ASDI), serial clock (DCLK), and chip select (*n*CS). Table 3–23 lists the serial configuration device's pin descriptions.

Figure 3–21 shows the Altera serial configuration device 8-pin SOIC package and its pin-out diagram.

Figure 3–21.	Altera Serial Configuration	Device 8-Pin SOIC	Package Pin-Out Diagram
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EF		EPCS CS16	4,
nCS —	1	8	- v <sub>cc</sub>
data —	2	7	- v <sub>cc</sub>
V <sub>CC</sub>	3	6	- DCLK
GND —	4	5	— ASDI

Figure 3–22 shows the Altera serial configuration device 16-pin SOIC package and its pin-out diagram.

Figure 3–22.	Altera Serial Configuration	Device 16-Pin SOIC Pa	ackage Pin-Out Diagram
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EPCS16, EPCS64, or EPCS128 1 16 DCLK V<sub>CC</sub> -2 15 ASDI V<sub>CC</sub> -N.C. 3(1) 14(1) N.C. N.C. 4(1) 13(1) N.C. N.C. -5<sup>(1)</sup> 12<sup>(1)</sup> N.C. N.C. — 6<sup>(1)</sup> 11<sup>(1)</sup> N.C. nCS \_\_\_\_\_ 7 10 \_\_\_\_ GND DATA - 8 9 \_ -v<sub>cc</sub>

### Note to Figure 3-22:

(1) These pins can be left floating or connected to  $V_{CC}$  or GND, whichever is more convenient on the board.

Table 3–23. Serial Configuration Device Pin Description (Part 1 of 2)

Pin Name	Pin Number in 8-Pin SOIC Package	Pin Number in 16-Pin SOIC Package	Pin Type	Description
DATA	2	8	Output	The DATA output signal transfers data serially out of the serial configuration device to the FPGA during read/configuration operation. During read/configuration operations, the serial configuration device is enabled by pulling $n$ CS low. The DATA signal transitions on the falling edge of DCLK.
ASDI	5	15	Input	The AS data input signal is used to transfer data serially into the serial configuration device. It receives the data that should be programmed into the serial configuration device. Data is latched on the rising edge of DCLK.

Pin Name	Pin Number in 8-Pin SOIC Package	Pin Number in 16-Pin SOIC Package	Pin Type	Description
nCS	1	7	Input	The active low chip select input signal toggles at the beginning and end of a valid instruction. When this signal is high, the device is deselected and the DATA pin is tri-stated. When this signal is low, it enables the device and puts the device in an active mode. After power up, the serial configuration device requires a falling edge on the $nCS$ signal before beginning any operation.
DCLK	6	16	Input	DCLK is provided by the FPGA. This signal provides the timing of the serial interface. The data presented on ASDI is latched to the serial configuration device on the rising edge of DCLK. Data on the DATA pin changes after the falling edge of DCLK and is latched into the FPGA on the next falling edge.
V <sub>CC</sub>	3, 7, 8	1, 2, 9	Power	Power pins connect to 3.3 V.
GND	4	10	Ground	Ground pin.

Table 3-23. Serial Configuration Device Pin Description (Part 2 of 2)

As shown in Figure 3–21 and Figure 3–22, the serial configuration device is an 8-pin or 16-pin device. In order to take advantage of vertical migration from EPSCS1 to EPCS128, Altera recommends a layout for serial configuration devices.

Figure 3–23. Layout Recommendation for Vertical Migration from EPCS1 to EPCS128



# **Package**

EPCS1 and EPCS4 available in 8-pin small outline integrated circuit (SOIC) package. EPCS16 available in 8-pin and 16-pin small outline integrated circuit (SOIC) packages. EPCS64 and EPCS128 available in 16-pin small outline integrated circuit (SOIC) package.

• For more information about Altera device packaging including mechanical drawing and specifications for this package, refer to the *Altera Device Package Information Data Sheet*.

# **Ordering Code**

Table 3–24 lists the ordering codes for serial configuration devices.

**Table 3–24.** Serial Configuration Device Ordering Codes

Device	Ordering Code (1)
EPCS1	EPCS1SI8
	EPCS1SI8N
EPCS4	EPCS4SI8
	EPCS4SI8N
EPCS16	EPCS16SI16N
	EPCS16SI8N
EPCS64	EPCS64SI16N
EPCS128	EPCS128SI16N

Note to Table 3-24:

(1) N: Lead free.

# **Chapter Revision History**

Table 3–25 lists the revision history for this chapter.

**Table 3–25.** Chapter Revision History (Part 1 of 3)

Date	Version	Changes Made
December 2009	3.3	<ul> <li>Updated "Features" and "Functional Description" sections.</li> </ul>
		Added "Fast Read Operation" section.
		Removed Table 4–2 to Table 4–9, Table 4-26, and Table 4–33.
		Updated Table 3-1.
		■ Updated Figure 3–2.
		<ul> <li>Removed "Referenced Documents" section.</li> </ul>
October 2008	3.2	<ul> <li>Updated "Introduction", "Active Serial FPGA Configuration", "Operation Codes", "Read Status Operation", "Read Device Identification Operation", and "Package" sections.</li> </ul>
		■ Updated Table 4–10, Table 4–25, Table 4–26, and Table 4–32.
		■ Updated Figure 4–5, Figure 4–13, and Figure 4–19.
		Added Figure 4–22.
		Added Table 4–33.
		<ul> <li>Updated new document format.</li> </ul>
May 2008	3.1	■ Updated Table 4–3, Table 4–6, Table 4–7, Table 4–28, and Table 4–29.
		<ul> <li>Deleted Note 5 to Table 4–31.</li> </ul>
		<ul> <li>Added "Referenced Documents" section.</li> </ul>

Date	Version	Changes Made		
August 2007	3.0	<ul> <li>Updated "Introduction" section.</li> </ul>		
		<ul> <li>Updated "Functional Description" section.</li> </ul>		
		<ul> <li>Updated Table 4–1 through Table 4–4 and Table 4–7 through Table 4–9 to with EPCS128 information.</li> </ul>		
		<ul> <li>Added Table 4–6 on Arria GX.</li> </ul>		
		<ul> <li>Added notes to Figure 4–3.</li> </ul>		
		<ul> <li>Added notes to Figure 4–4.</li> </ul>		
		<ul> <li>Updated Table 4–10 with EPCS128 information.</li> </ul>		
		Added new Table 4–11 on address range for sectors in EPCS128 device.		
		<ul> <li>Updated Table 4–16 with information about "Read Device Identification" and added (Note 5).</li> </ul>		
		<ul> <li>Added new Table 4–21 on block protection bits in EPCS128.</li> </ul>		
		<ul> <li>Added notes to Figure 4–12.</li> </ul>		
		<ul> <li>Added new section "Read Device Identification Operation" with Table 4–23 and Figure 4–13.</li> </ul>		
		<ul> <li>Updated "Write Bytes Operation", "Erase Bulk Operation" and "Erase Sector Operation" sections.</li> </ul>		
		<ul> <li>Updated Table 4–24 to include EPCS128 information.</li> </ul>		
		<ul> <li>Updated (Note 1) to Table 4–26.</li> </ul>		
		<ul> <li>Updated VCC and VI information to include EPCS128 in Table 4–27.</li> </ul>		
		<ul> <li>Updated VIH information to include EPCS128 in Table 4–29.</li> </ul>		
		<ul> <li>Updated ICC0 and ICC1 information to include EPCS128 in Table 4–30.</li> </ul>		
		<ul> <li>Updated Figure 4–21 and Table 4–34 with EPCS128 information.</li> </ul>		
April 2007	2.0	<ul> <li>Updated "Introduction" section.</li> </ul>		
		<ul> <li>Updated "Functional Description" section and added handpara note.</li> </ul>		
		Added Table 4–4, Table 4–6, and Table 4–7.		
		<ul> <li>Updated "Active Serial FPGA Configuration" section and its handpara note.</li> </ul>		
		<ul> <li>Added notes to Figure 4–2.</li> </ul>		
		<ul> <li>Updated Table 4–26 and added (Note 1).</li> </ul>		
		<ul> <li>Updated Figure 4–20.</li> </ul>		
		<ul> <li>Updated Table 4–34.</li> </ul>		
January 2007	1.7	<ul> <li>Removed reference to PLMSEPC-16 in "Programming and Configuration File Support".</li> </ul>		
		<ul> <li>Updated DCLK pin information in Table 4–32.</li> </ul>		
October 2006	1.6	<ul> <li>Updated Figure 4–19.</li> </ul>		
		Updated Table 4–30 and Table 4–32.		
August 2005	1.5	<ul> <li>Updated table 4-4 to include EPCS64 support for Cyclone devices.</li> </ul>		
August 2005	1.4	Updated tables.		
		Minor text updates.		
February 2005	1.3	<ul> <li>Updated hot socketing AC specifications.</li> </ul>		

**Table 3–25.** Chapter Revision History (Part 2 of 3)

Date	Version	Changes Made
October 2003	1.2	<ul> <li>Added Serial Configuration Device Memory Access section.</li> </ul>
		<ul> <li>Updated timing information in Tables 4–10 and 4–11 section.</li> </ul>
		Updated timing information in Tables 4-16 and 4-17.
July 2003	1.1	<ul> <li>Minor updates.</li> </ul>
May 2003	1.0	Added document to the <i>Cyclone Device Handbook.</i>

## **Table 3–25.** Chapter Revision History (Part 3 of 3)